

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

EPAS ID: PAT6779284

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SIEW KIT HOI	06/21/2021
RECEIVING PARTY DATA	
Name:	APPLIED MATERIALS SINGAPORE TECHNOLOGY PTE. LTD.
Street Address:	8 UPPER CHANGI ROAD NORTH
Internal Address:	APPLIED MATERIALS BUILDING
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	506906
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17351535
CORRESPONDENCE DATA	
Fax Number:	(732)935-7122
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	732-935-7100
Email:	lzaveta@mtiplaw.com
Correspondent Name:	MOSER TABOADA/ALAN TABOADA
Address Line 1:	1030 BROAD STREET
Address Line 2:	SUITE 203
Address Line 4:	SHREWSBURY, NEW JERSEY 07702
ATTORNEY DOCKET NUMBER:	44019244US1
NAME OF SUBMITTER:	ALAN TABOADA
SIGNATURE:	/ALAN TABOADA/
DATE SIGNED:	06/24/2021
Total Attachments: 2	
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ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Name and Address
of Inventor:

Siew Kit HOI

Applied Materials Singapore Technology Pte Ltd.
10 Science Park Rd 02-01B The Alpha Science Park 2
Singapore 117684

(hereinafter referred to as Assignor), has invented a certain invention entitled:

**PROCESS KIT HAVING TALL DEPOSITION RING AND SMALLER DIAMETER
ELECTROSTATIC CHUCK (ESC) FOR PVD CHAMBER**

for which I have filed an application for a Patent of the United States on June 18, 2021, Serial No. 17/351,535; and

WHEREAS, Applied Materials Singapore Technology Pte. Ltd., a company organized under the laws of Singapore, having a place of business at 8 Upper Changi Road North, Applied Materials Building, Singapore 506906 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignor, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignor hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignor hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignor shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon,

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including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignor, his respective heirs, legal representatives and assigns.

4. Said Assignor hereby warrant and represent that he has not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignor have executed and delivered this instrument to said Assignee on the dates indicated below.

6/21/2021
_____ (Date)

DocuSigned by:

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Siew Kit HOI

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